



- Fully compatible with IEEE 802.3bj and IEEE 802.3cd
- 100 Ohm differential impedance system
- Allows for 25Gb/s and 50Gb/s per channel transmission, aggregate of 200Gb/s and 400Gb/s total bandwidth
- Optimized PCB interface board to minimize crosstalk and insertion loss
- Robust diecast covers for superior EMI shielding effectiveness
- EEPROM for cable signature & system communications
- BER better than 10^{-15}
- 30 AWG to 28AWG cable sizes available
- RoHS compliant



Direct Attach Cable

400G QSFP-DD

Applications

- Servers
- Networked storage system
- Routers
- External storage system
- High performance computing application
- Data center networking

Specifications

Differential Impedance	100 +/- 10 Ohm
Supply Voltage	3.3V (Typical)
Operating Temperature	0°C to 70°C
Storage Temperature	-20°C to 80°C
Durability	50 cycles
Mating Force	40N max. (Insertion Force), 30N max. (Extraction Force)
Module Retention	125N min.
Bend Radius	5x cable OD min.

Part Series List

Length (M)	Passive/Active	Conductor Material	Gauge
1	Passive	Copper	30
2	Passive	Copper	28
2.5	Passive	Copper	28



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